

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name, and I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: ENHANCED CHIP SCALE PACKAGE FOR FLIP CHIPS, the specification of which (check applicable box(es):

[X]is attached hereto; I lwas filed on	f	as U.S. Application Serial No	
] was filed as PCT international applicable to U.S. or PCT applica-	application No. PCT/	/on	and (if
	iewed and understand the co	ontents of the above-identified spove.	ecification, including
accordance with 37 C.F.R. 1. foreign application(s) for pater	.56(a). I hereby claim foreignt or inventor's certificate list for's certificate having a filing	s material to the patentability of gn priority benefits under 35 U.S sed below and have also identified date before that of the application his application:	i.C. 119/365 of any
Application Number	Country	Day/Month/Year Filed	
listed below and, insofar as th prior application in the manne	ne subject matter of each of er provided by the first para as defined in 37 C.F.R. 1.56(orior United States and PCT interrate claims of this application is no graph of 35 U.S.C. 112, I acknow which occurred between the fille of this application:	ot disclosed in such wiledge the duty to
	Day/Month/Year Filed	Status: patented, pending	ı, abandoned
information and belief are belie That willful false statements and	eved to be true, and further to dithe like so made are punish Code and that such willful	mowledge are true and that all si that these statements were made lable by fine or imprisonment, or b false statements may jeopardize	with the knowledge oth, under \$1001 of
Number 24112 in the records	of the United States Patent ation and to transact all busi	oats & Bennett, P.L.L.C., as ider and Trademark Office and as up ness in the Patent and Trademan . Coats).	odated from time to
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) Inventor's Signature	phyla	Date13/7/0	
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